

Customer Process Change Notification Form PCN-2010-403

Part Information

Cirrus Logic Part # / Quantity

CS495303-CVZ
 CS495313-CVZ
 CS495304-CVZ
 CS495314-CVZ
 CS497004-CVZ
 CS497014-CVZ
 CS497024-CVZ
 CS49DV8C-CVZ

PCN Effective Date: Lot Effective Date:

Cirrus P/N Change: Yes No (Contact the sales representative for availability of samples if applicable)

If yes, provide new part number:

Additional Part Number (use if more space is needed)

Package Mark Change: Yes No

If Yes, briefly explain:

[Any Fab, Assembly, or Design changes results in pack mark changes, please provide detail]

- | | | |
|---------------------------|---|---|
| Reason for Change: | <input type="checkbox"/> Design/New Rev | <input type="checkbox"/> Fab Process |
| | <input type="checkbox"/> Assembly Site | <input type="checkbox"/> Additional Assembly Source |
| | <input type="checkbox"/> Fab Site | <input type="checkbox"/> Assembly Process |
| | <input checked="" type="checkbox"/> Other (Specify) | <input type="checkbox"/> Additional Fab Source |

Current qualified leadframe supplier for the 128 LQFP package assembled at SPIL is ending production on the current frame effective 7/31/2010. Leadframe will be sourced from an alternate qualified supplier beginning in December 2010.

- | | | |
|-------------------------------|---|--|
| Description of Change: | <input type="checkbox"/> Fix Errata | <input type="checkbox"/> Yield Enhancement |
| | <input type="checkbox"/> Fix Known Bug | <input type="checkbox"/> Performance Improvement |
| | <input checked="" type="checkbox"/> Other (specify) | |

Adoption of the new leadframe source will result in a die flag size change for the 128 LD LQFP 14x20 mm package. There will be no change to the external package dimensions. There will be no change to the other packaging bill of materials (mold compound, wire, die attach epoxy, plating, leadframe alloy).

Additional Information



SPIL 128 LQFP
Leadframe Flag
Size Details.ppt
503.5 KB

Quality and Reliability Impact:

Qualification Data Required? Yes No

Additional Information



Reliability
Qualification
Report
QRR100801.pdf
25.97 KB

Data Sheet Change Required? Yes No

If Yes, briefly explain:

Additional Information

[Click here to attach a file](#)

Software Change Required? Yes No

If Yes, briefly
explain:

Additional Information

[Click here to attach a file](#)

Customer Acknowledgement and Agreement

Acknowledged and Agreed as of the Date written below:

Customer Company _____
Name:

Customer Contact _____
Name:

Title: _____

Signature: _____

Date:

Customer Agreed Customer Reject Not Applicable

Customer Comments:

128 LQFP 14x20 mm Leadframe Comparison by Part Number

Device / Revision	Current Leadframe Flag Size	New Leadframe Flag Size
CS495303-CVZ / C	315 x 315 mils	236 x 292 mils
CS495303-CVZ / D	315 x 315 mils	268 x 268 mils
CS495313-CVZ / C	315 x 315 mils	236 x 292 mils
CS495313-CVZ / D	315 x 315 mils	268 x 268 mils
CS495304-CVZ / D	315 x 315 mils	268 x 268 mils
CS495314-CVZ / D	315 x 315 mils	268 x 268 mils
CS497004-CVZ / C	315 x 315 mils	236 x 292 mils
CS497004-CVZ / D	315 x 315 mils	268 x 268 mils
CS497014-CVZ / D	315 x 315 mils	268 x 268 mils
CS497024-CVZ / C	315 x 315 mils	236 x 292 mils
CS497024-CVZ / D	315 x 315 mils	268 x 268 mils
CS49DV8C-CVZ / C	315 x 315 mils	236 x 292 mils
CS49DV8C-CVZ / D	315 x 315 mils	268 x 268 mils

CONFIDENTIAL INFORMATION



Reliability Report: QRR100801
Subject/Purpose:

Qualify the 128 LQFP package assembled at Siliconware using qualification stress testing performed on a 100 LQFP and 144 LQFP.

APPROVALS:

Mike Klucher

Reliability Engineering

Results:

Qualification successful.

STATUS:

Complete - Pass

<u>Stress</u>	<u>Conditions</u>	<u>Method</u>	<u>Duration</u>	<u>Lot</u>	<u>Results (Fail/Sample)</u>
Precondition MSL-3	24HR 125 °C Bake	JESD22-A113	Precondition	1	0/231
QJ1778	192HR 30°C/60%RH Soak		Precondition	2	0/231
QJ1780	3 pass 260 °C Convection		Precondition	3	0/77
QJ1898	reflow				
HAST	130 °C	JESD22-A110	96 Hours	1	0/77
QJ1778	85 %RH				
	1.95 Volts				
	3.5 Volts				
THB	85 °C	JESD22-A101	500 Hours	1	0/77
QJ1780	85 %RH		1000 Hours	1	0/77
QJ1898	1.95 Volts		500 Hours	2	0/77
	3.5 Volts		1000 Hours	2	0/77
Temperature Cycle cond. C	-65 °C	JESD22-A104	500 Cycles	1	0/77
QJ1778	+150 °C		500 Cycles	2	0/77
QJ1780	air to air				
Tomography (CSAM)		J-STD-035	Post Temp Cycle	1	0/11
QJ1778			Post Temp Cycle	2	0/11
QJ1780					

Background Information:

Package: 128LQFP

Assembly: Siliconware (Taiwan)

Lead Finish: Pb-free



<u>Stress</u>	<u>Conditions</u>	<u>Method</u>	<u>Duration</u>	<u>Lot</u>	<u>Results (Fail/sample)</u>
Autoclave/PPOT	121 °C	JESD22-A102	96 Hours	1	0/77
QJ1778	15 psig		96 Hours	2	0/77
QJ1780	100% R.H.				
Solderability	93 °C steam aging	JESD22-B102	Solderability	1	0/15
QJ1778	8 Hours		Solderability	2	0/15
QJ1780	245 °C solder bath				
	5 Seconds				
HTSL (High Temp Storage Life)	150 °C	JESD22-A103	500 Hours	1	0/77
QJ1778			1000 Hours	1	0/77
QJ1780			500 Hours	2	0/77
			1000 Hours	2	0/77

Background Information:

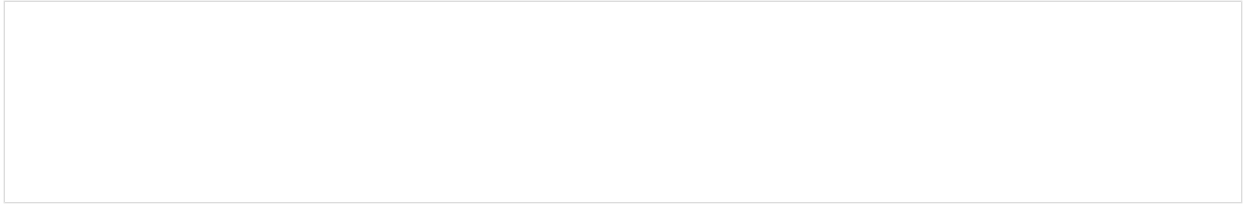
Package: 128LQFP


Assembly: Siliconware (Taiwan)

Lead Finish: Pb-free

Prepared by: Genesis Krzyzaniak

CONFIDENTIAL



	Title: CUSTOMER PROCESS CHANGE NOTIFICATION FORM		
	Digitally Signed By:	Doc No: 4-QUAL-00017	Rev: D

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